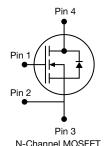
Vishay Siliconix



E Series Power MOSFET

PRODUCT SUMMARY					
V _{DS} (V) at T _J max.	700				
R _{DS(on)} typ. (Ω) at 25 °C	$V_{GS} = 10 V$	0.316			
Q _g max. (nC)	68				
Q _{gs} (nC)	9				
Q _{gd} (nC)	15				
Configuration	Single				





N-Channel MOSFET

FEATURES

- Low figure-of-merit (FOM) Ron x Qa
- Low input capacitance (Ciss)
- · Reduced switching and conduction losses
- Ultra low gate charge (Q_q)
- Avalanche energy rated (UIS)
- · Kelvin connection for reduced gate noise
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

APPLICATIONS

- · Server and telecom power supplies
- Switch mode power supplies (SMPS)
- Power factor correction power supplies (PFC)
- Lighting
 - High-intensity discharge (HID)
 - Fluorescent ballast lighting
- Industrial
 - Welding
 - Induction heating
 - Motor drives
 - Battery chargers
 - Renewable energy
 - Solar (PV inverters)

ORDERING INFORMATION	
Package	PowerPAK 8 x 8
Lead (Pb)-free and Halogen-free	SiHH11N65E-T1-GE3

ABSOLUTE MAXIMUM RATINGS (T _C = 25 °C, unl	ess otherwis	se noted)		
PARAMETER			SYMBOL	LIMIT	UNIT
Drain-Source Voltage			V _{DS}	650	v
Gate-Source Voltage			V _{GS}	± 30	V
Continuous Drain Current (T _J = 150 °C)	\/t = t 10 \/	T _C = 25 °C T _C = 100 °C	- I _D	12	
	V _{GS} at 10 V	T _C = 100 °C		8	А
Pulsed Drain Current ^a			I _{DM}	27	
Linear Derating Factor				1	W/°C
Single Pulse Avalanche Energy ^b			E _{AS}	127	mJ
Maximum Power Dissipation			PD	130	W
Operating Junction and Storage Temperature Range		T _J , T _{stg}	-55 to +150	°C	
Drain-Source Voltage Slope	T _J = 1	T _J = 125 °C		70	V/ns
Reverse Diode dV/dt ^c			dV/dt	24	v/ns

Notes

a. Repetitive rating; pulse width limited by maximum junction temperature.

b. V_{DD} = 140 V, starting T_J = 25 °C, L = 28.2 mH, R_q = 25 Ω , I_{AS} = 3 A.

c. $I_{SD} \leq I_D$, dl/dt = 100 A/µs, starting T_J = 25 °C.

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THERMAL RESISTANCE RATI	NGS							
PARAMETER	SYMBOL	TYP.		MAX.			UNIT	
Maximum Junction-to-Ambient	R _{thJA}	42		55			00 AM	
Maximum Junction-to-Case (Drain)	R _{thJC}	0.72		0.96			°C/W	
		·						
SPECIFICATIONS (T _J = 25 °C, u	nless otherwi	se noted)						
PARAMETER	SYMBOL		T CONDITI	ONS	MIN.	TYP.	MAX.	UNIT
Static							1	<u> </u>
Drain-Source Breakdown Voltage	V _{DS}	V _{GS} =	= 0 V, I _D = 2	50 µA	650	-	-	V
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	Referenc	e to 25 °C,	I _D = 1 mA	-	0.77	-	V/°C
Gate-Source Threshold Voltage (N)	V _{GS(th)}	V _{DS} =	V_{GS} , $I_D = 2$	50 μA	2	-	4	V
Osta Cauraa Laakaana		$V_{GS} = \pm 20 \text{ V}$		V	-	-	± 100	nA
Gate-Source Leakage	e-Source Leakage I _{GSS} V _{GS} = ± 30 V		V	-	-	± 1	μA	
	1-	V _{DS} =	650 V, V _{GS}	s = 0 V	-	-	1	μA
Zero Gate Voltage Drain Current	IDSS	V _{DS} = 520 V	, V _{GS} = 0 V	, T _J = 125 °C	-	-	50	
Drain-Source On-State Resistance	R _{DS(on)}	$V_{GS} = 10 V$	ار	_D = 6 A	-	0.316	0.363	Ω
Forward Transconductance	9 _{fs}	V _{DS}	= 30 V, I _D =	= 6 A	-	4.1	-	S
Dynamic								
Input Capacitance	C _{iss}		$V_{GS} = 0 V,$		-	1257	-	
Output Capacitance	C _{oss}	Ň	/ _{DS} = 100 V		-	60	-	
Reverse Transfer Capacitance	C _{rss}		f = 1 MHz		-	4	-]
Effective Output Capacitance, Energy Related ^a	C _{o(er)}	V_{DS} = 0 V to 520 V, V_{GS} = 0 V		-	43	-	pF	
Effective Output Capacitance, Time Related ^b	C _{o(tr)}			-	168	-		
Total Gate Charge	Qg				-	34	68	
Gate-Source Charge	Q _{gs}	$V_{GS} = 10 V$	I _D = 6 A	, V _{DS} = 520 V	-	9	-	nC
Gate-Drain Charge	Q _{gd}				-	15	-	
Turn-On Delay Time	t _{d(on)}				-	19	38	
Rise Time	t _r	V _{DD} =	= 520 V, I _D =	= 6 A,	-	28	56	ns
Turn-Off Delay Time	t _{d(off)}	V _{GS} =	10 V, R _g =	9.1 Ω	-	39	78	110
Fall Time	t _f				-	23	46	
Gate Input Resistance	R _g	f = 1	MHz, open	drain	0.3	0.7	1.4	Ω
Drain-Source Body Diode Characteristic	s				1	1		-
Continuous Source-Drain Diode Current	I _S	MOSFET symbol showing the integral reverse p - n junction diode		-	-	12	A	
Pulsed Diode Forward Current	I _{SM}			-	-	27		
Diode Forward Voltage	V _{SD}	T _J = 25 °	C, I _S = 6 A,	$V_{GS} = 0 V$	-	0.9	1.2	V
Reverse Recovery Time	t _{rr}			- 6 ^	-	321	642	ns
Reverse Recovery Charge	Q _{rr}	T _J = 25 °C, I _F = I _S = 6 A, dl/dt = 100 A/μs, V _B = 25 V		-	3.8	7.6	μC	
Reverse Recovery Current	I _{RRM}		· F -) -		-	19	-	Α

Notes

a. $C_{oss(er)}$ is a fixed capacitance that gives the same energy as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DS} .

b. $C_{oss(tr)}$ is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DS} .





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TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

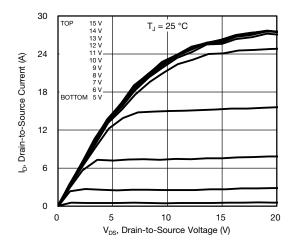


Fig. 1 - Typical Output Characteristics

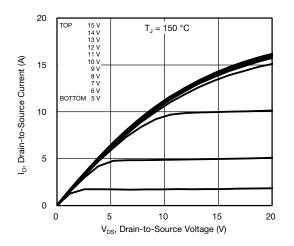
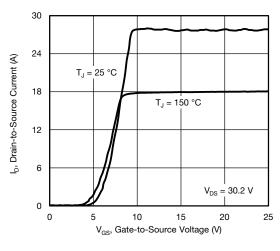


Fig. 2 - Typical Output Characteristics





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Fig. 4 - Normalized On-Resistance vs. Temperature

T_J, Junction Temperature (°C)

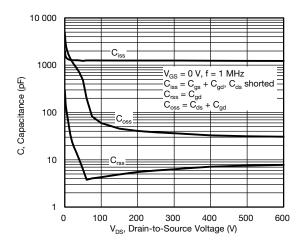


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

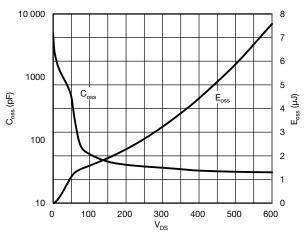


Fig. 6 - C_{OSS} and E_{OSS} vs. V_{DS}

3 For technical questions, contact: <u>hvm@vishay.com</u>

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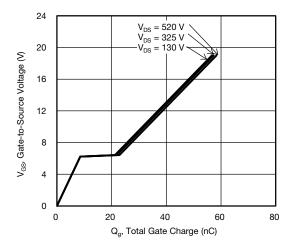


Fig. 7 - Typical Gate Charge vs. Gate-to-Source Voltage

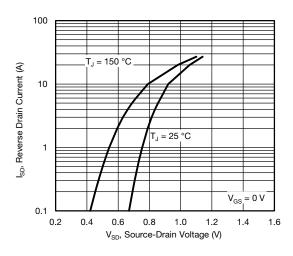


Fig. 8 - Typical Source-Drain Diode Forward Voltage

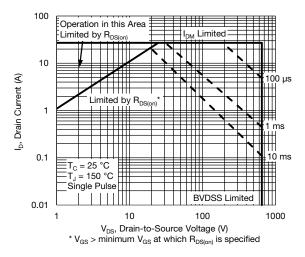


Fig. 9 - Maximum Safe Operating Area

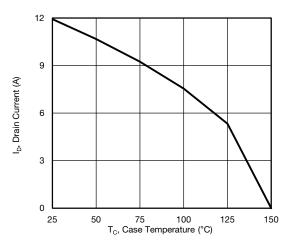


Fig. 10 - Maximum Drain Current vs. Case Temperature

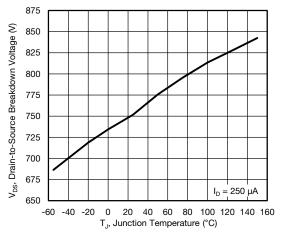


Fig. 11 - Temperature vs. Drain-to-Source Voltage

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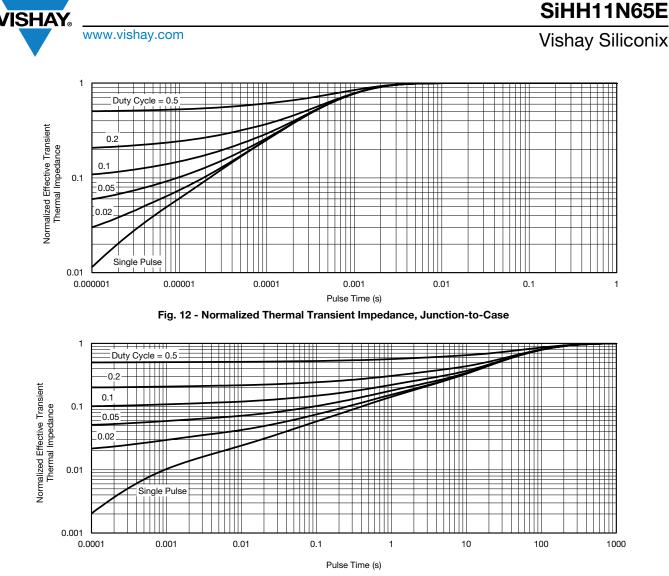


Fig. 13 - Normalized Thermal Transient Impedance, Junction-to-Ambient

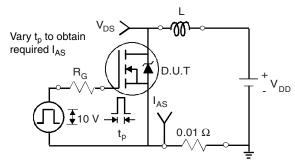


Fig. 14 - Switching Time Test Circuit

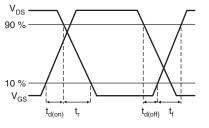


Fig. 15 - Switching Time Waveforms

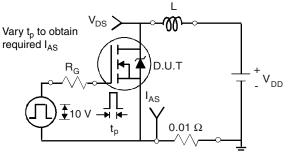


Fig. 16 - Unclamped Inductive Test Circuit

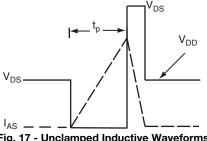
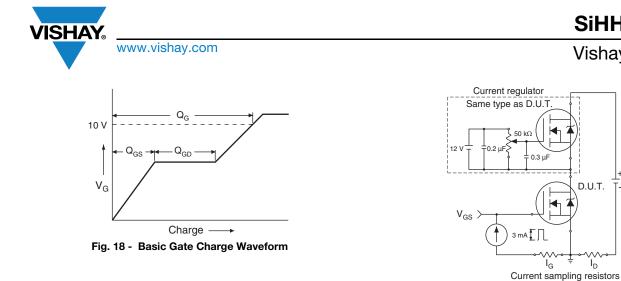


Fig. 17 - Unclamped Inductive Waveforms

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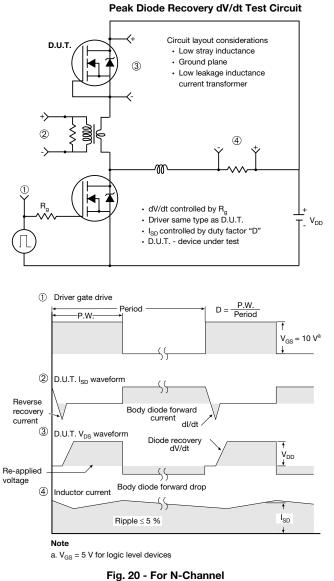
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 $V_{\rm DS}$

D.U.T. т

 I_D

Fig. 19 - Gate Charge Test Circuit



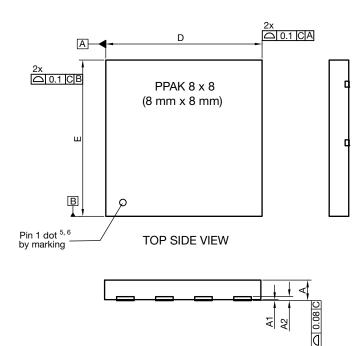
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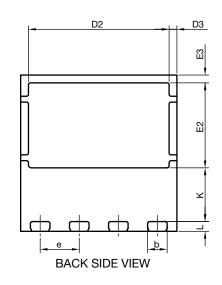
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PowerPAK[®] 8 x 8 Case Outline





DIM		MILLIMETERS			INCHES		
DIM. MIN.	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.	
А	0.95	1.00	1.05	0.037	0.039	0.041	
A1	0.00	-	0.05	0.000	-	0.002	
A2		020 ref.			0.008 ref.		
b	0.95	1.00	1.05	0.037	0.039	0.041	
D	7.90	8.00	8.10	0.311	0.315	0.319	
D2	7.10	7.20	7.30	0.280	0.283	0.287	
D3		0.40 BSC			0.016 BSC		
е	2.00 BSC			0.079 BSC			
E	7.90	8.00	8.10	0.311	0.315	0.319	
E2	4.30	4.35	4.40	0.169	0.171	0.173	
E3	0.40 BSC				0.016 BSC		
К	2.75 BSC		0.108 BSC				
L	0.45	0.50	0.55	0.018	0.020	0.022	
N ⁽³⁾	8				8		

Notes

⁽¹⁾ Use millimeters as the primary measurement

⁽²⁾ Dimensioning and tolerances conform to ASME Y14.5 M - 1994

⁽³⁾ N is the number of terminals

⁽⁴⁾ The pin 1 identifier must be existed on the top surface of the package by using indentation mark or other feature of package body

⁽⁵⁾ Exact shape and size of this feature is optional

ECN: E20-0518-Rev. B, 28-Sep-2020 DWG: 6041

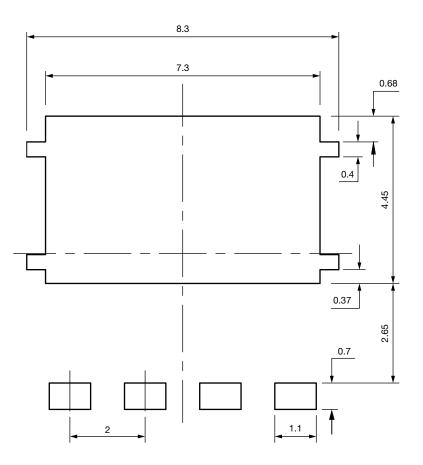
Revision: 28-Sep-2020

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Recommended Minimum PADs for PowerPAK[®] 8 mm x 8 mm



Dimensions in millimeters



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